

# SOT1069-1

plastic thermal enhanced very very thin small outline  
package; no leads; 8 terminals; body 2 x 3 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HWSO8
<b>Package type industry code</b>	HWSO8
<b>Package style descriptive code</b>	HWSO8 (thermal enhanced very very thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-229
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	10-8-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	0.8	0.8	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	

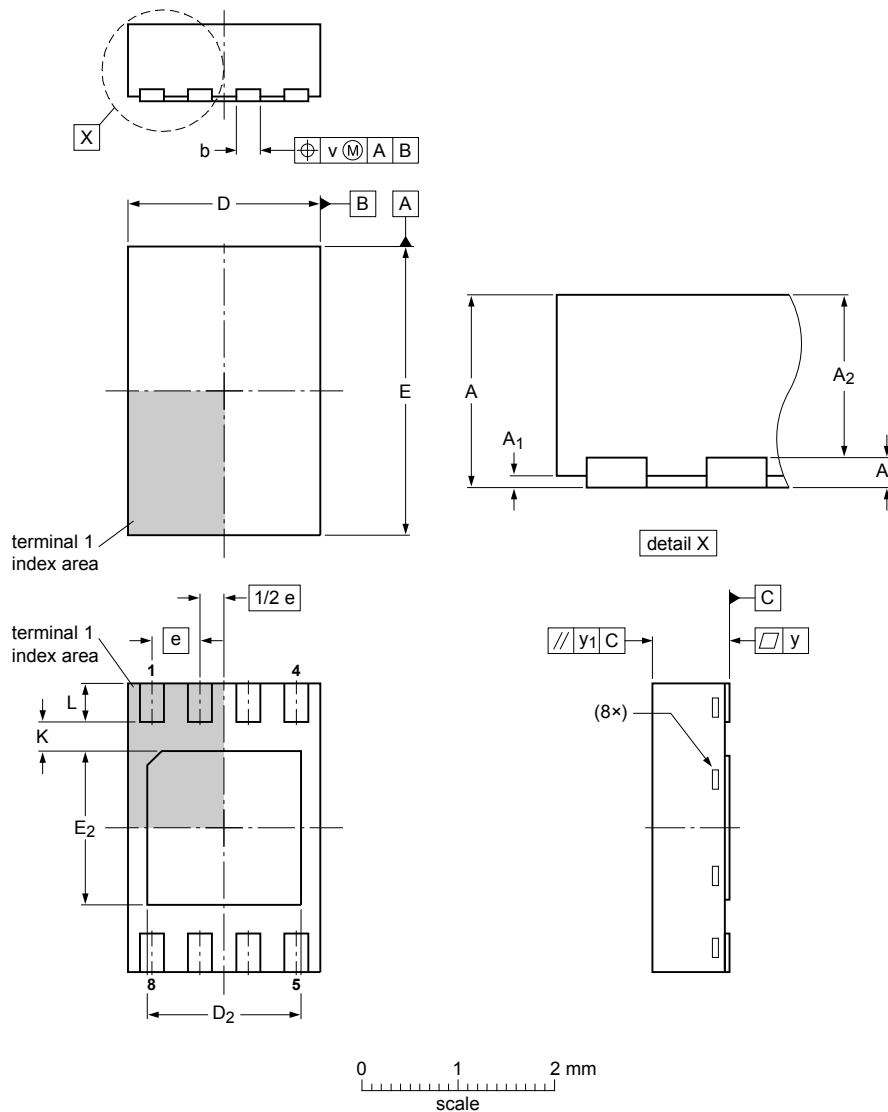


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## 2. Package outline

**HWSO8: plastic thermal enhanced very very thin small outline package; no leads; 8 terminals; body 2 x 3 x 0.8 mm**

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**Dimensions**

Unit	A <sup>(1)</sup>	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b	D	D <sub>2</sub>	E	E <sub>2</sub>	e	K	L	v	y	y <sub>1</sub>	
mm	max 0.80	0.05	0.65		0.30	2.1	1.6	3.1	1.6					0.45		
	nom 0.75	0.02	0.55	0.2	0.25	2.0		3.0		0.5				0.1	0.05	0.05
	min 0.70	0	0.45		0.20	1.9	1.4	2.9	1.4		0.2	0.35				

**Note**

1. Dimension A is including plating thickness. The package footprint is compatible with JEDEC MO229

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1069-1		MO-229			<del>08-07-10</del> 09-08-10

**Fig. 1. Package outline HWSO8 (SOT1069-1)**

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### 3. Legal information

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